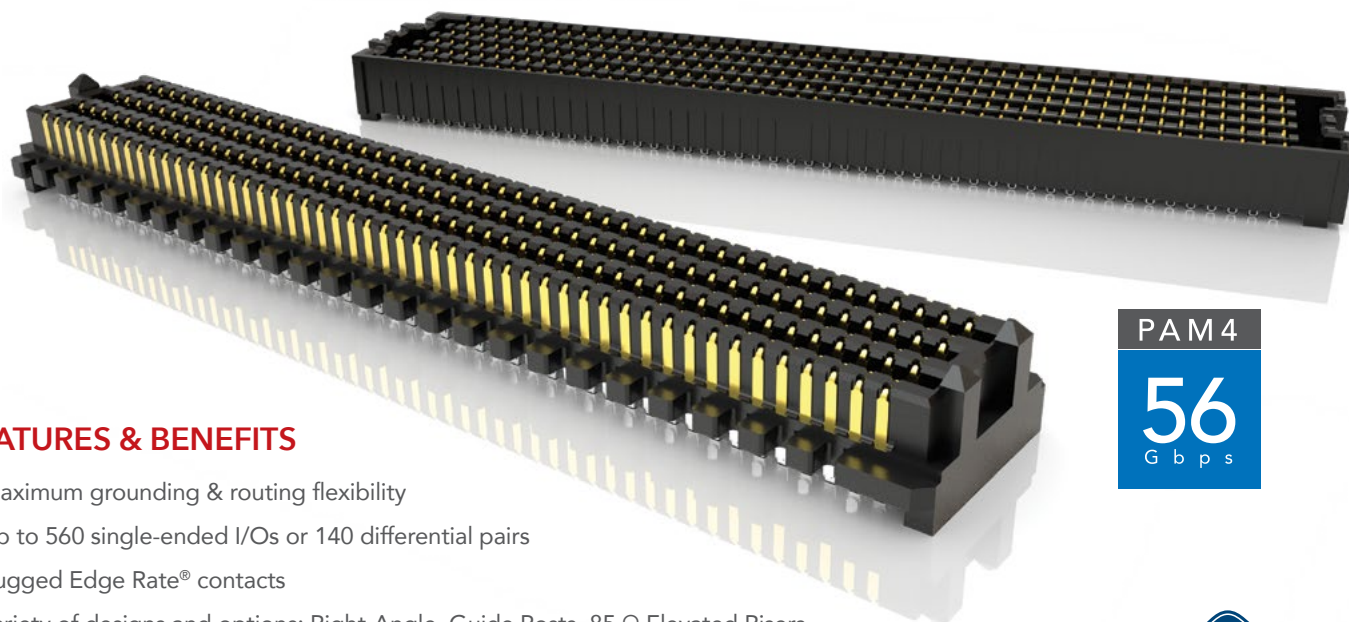




HIGH-DENSITY OPEN-PIN-FIELD ARRAYS

(1.27 mm) .050" PITCH

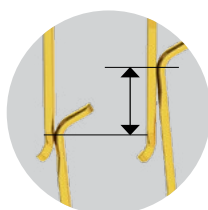


FEATURES & BENEFITS

- Maximum grounding & routing flexibility
- Up to 560 single-ended I/Os or 140 differential pairs
- Rugged Edge Rate® contacts
- Variety of designs and options: Right-Angle, Guide Posts, 85 Ω Elevated Risers, 85 Ω Tuned, Press-Fit and Press-Fit Right-Angle, Guide Post Field Termination Kits
- Compatible with UMPT/UMPS for power/signal flexibility
- Cable mates (SEAC Series) and Jack Screw Standoffs (JSO Series) also available
- Standards: VITA 47, VITA 57.1 FMC, VITA 57.4 FMC+, VITA 74 VNX, PISMO™ 2
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel & InfiniBand

PAM 4
56
G b p s

**EDGE
RATE**
CONTACT



(1.12 mm) .044"
Nominal Wipe

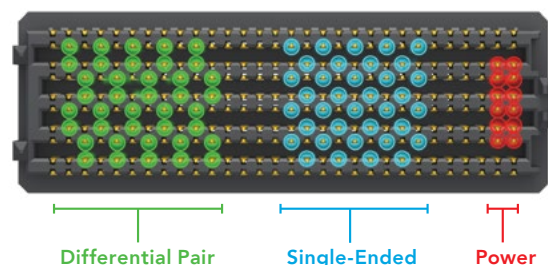


Solder Charges



Power / Signal
Applications

MAXIMUM GROUNDING & ROUTING FLEXIBILITY



KEY SPECIFICATIONS

PITCH	STACK HEIGHTS	TOTAL PINS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
1.27 mm x 1.27 mm	7 mm - 18.5 mm	40 - 560	Black LCP	Copper Alloy	Au or Sn over 50 μ " (1.27 μ m) Ni	-55 °C to +125 °C	2.7 A per pin (10 adjacent pins powered) 7 mm stack height	240 VAC	Yes

Note: Some lengths, styles and options are non-standard, non-returnable

(1.27 mm) .050" PITCH • SEAM/SEAF SERIES

SERIES	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	K	"X" R
SEAM Terminal	-10, -15, -20, -30, -40, -50	Specify LEAD STYLE from chart	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04 -05 -06 -08 -10	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge			
SEAF Socket	SEAM & SEAF: -10 only available in -04 Row SEAM: -15 only available in -04 Row with -02.0 Lead Style, and -10 Row with any Lead Style; SEAF: -15 only available in -04 or -10 Row with -5.0 Lead Style		-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	SEAM: -04, -05 & -06 (Rows not available with -06.5 Lead Style)				-A = Alignment Pin -K Polyimide Film Pick & Place Pad -TR = Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

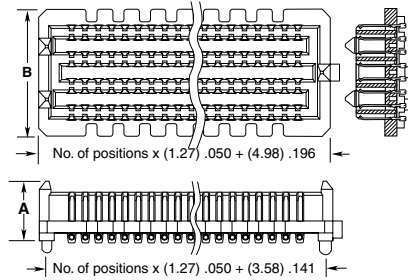
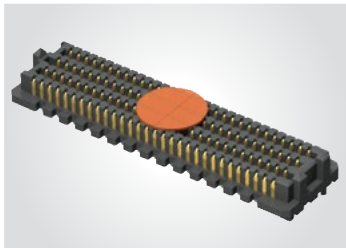
SEAM

Board Mates:

SEAF, SEAFP

Standoffs:

JSO



LEAD STYLE	A	NO. OF ROWS	B
-02.0	(5.61) .221	-04	(7.06) .278
-03.0	(6.60) .260	-05, -06	(9.60) .378
-03.5	(7.11) .280	-08	(12.14) .478
-06.5	(10.16) .400	-10	(14.68) .578
-07.0	(10.59) .417		
-09.0	(12.60) .496		
-11.0	(14.61) .575		

ALSO AVAILABLE

See website for 14 row option.

View complete specifications at: samtec.com?SEAM

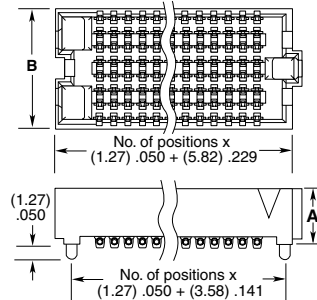
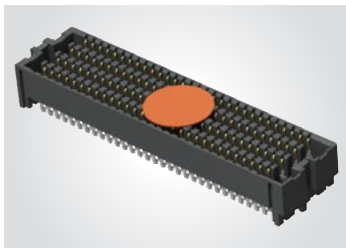
SEAF

Board Mates:

SEAM, SEAMP,
SEAR, SEAMI

Standoffs:

JSO



LEAD STYLE	A	NO. OF ROWS	B
-05.0	(5.05) .199	-04	(5.66) .223
-06.0	(6.05) .238	-05, -06	(8.20) .323
-06.5	(6.55) .258	-08	(10.74) .423
-07.5	(7.54) .297	-10	(13.28) .523

View complete specifications at: samtec.com?SEAF

MATED HEIGHTS

SEAM LEAD STYLE	SEAF LEAD STYLE			
	-05.0	-06.0	-06.5	-07.5
-02.0	7 mm	8 mm	8.5 mm	9.5 mm
-03.0	8 mm	9 mm	9.5 mm	10.5 mm
-03.5	8.5 mm	9.5 mm	10 mm	11 mm
-06.5	11.5 mm	12.5 mm	13 mm	14 mm
-07.0	12 mm	13 mm	13.5 mm	14.5 mm
-09.0	14 mm	15 mm	15.5 mm	16.5 mm
-11.0	16 mm	17 mm	17.5 mm	18.5 mm

STANDARDS

VITA 47
VITA 57.1 FMC
VITA 57.4 FMC+
VITA 74 VNX
PISMO™2

Visit www.samtec.com/standards for more information.

Notes:
IPC-A-610F and
IPC J-STD-001F Class 3 solder joint.